



SOT2017-1

X2SON4, super thin small outline; no leads, 4 terminals, 0.65 mm pitch, 1.6 mm x 1.6 mm x 0.32 mm body

8 May 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	X2SON4
Package style descriptive code	X2SON (super thin small outline; no leads)
JEDEC package outline code	MO-287
Mounting method type	S (surface mount)
Issue date	04-04-2019
Manufacturer package code	98ASA01421D

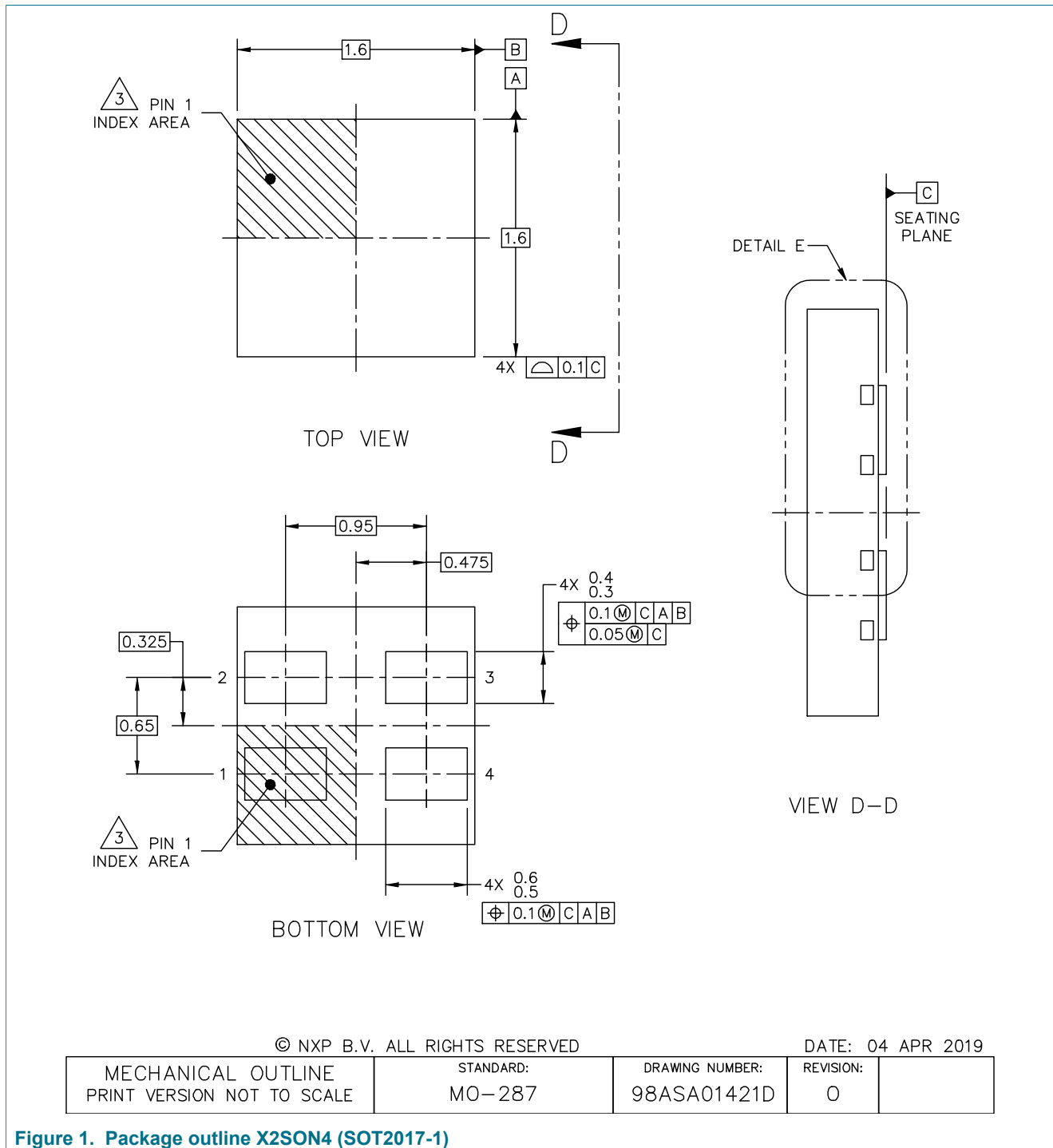
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	1.6	-	mm
package width	-	1.6	-	mm
seated height	-	0.32	-	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	4	-	

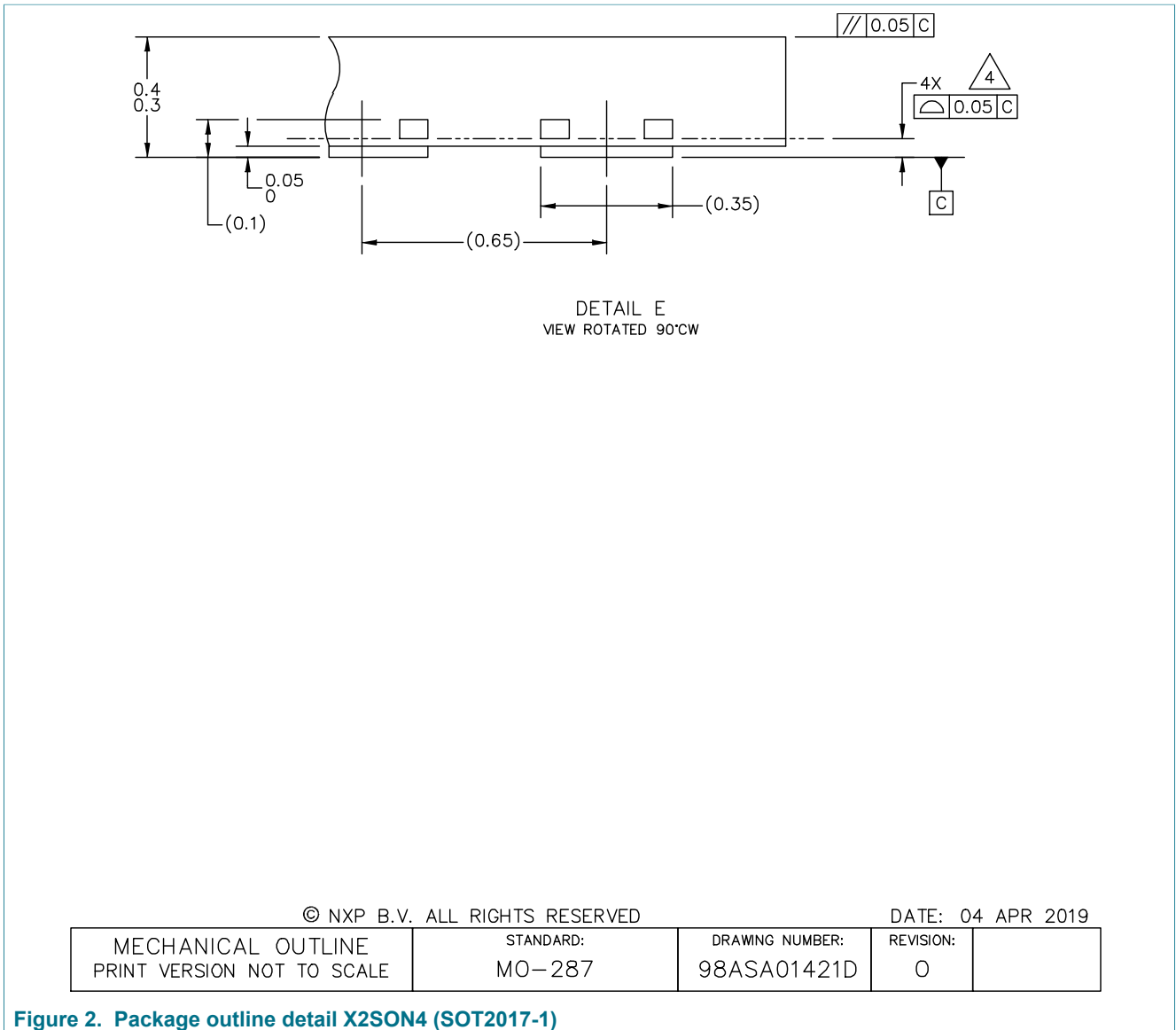


X2SON4, super thin small outline; no leads, 4 terminals, 0.65 mm pitch, 1.6 mm x 1.6 mm x 0.32 mm body

2 Package outline

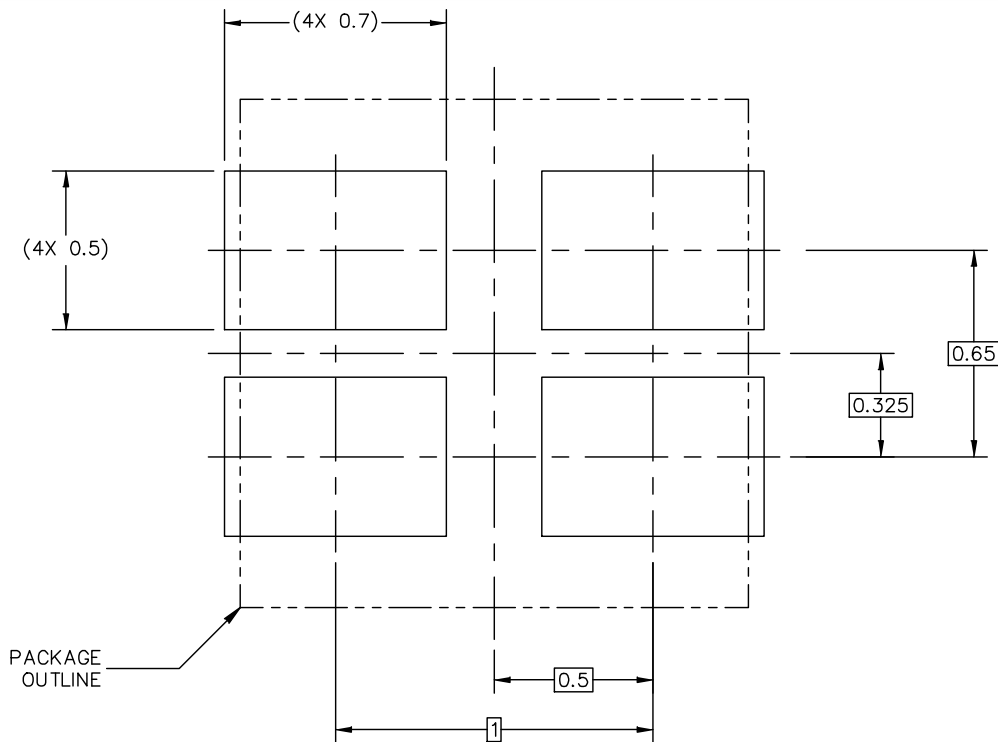


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3 Soldering



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

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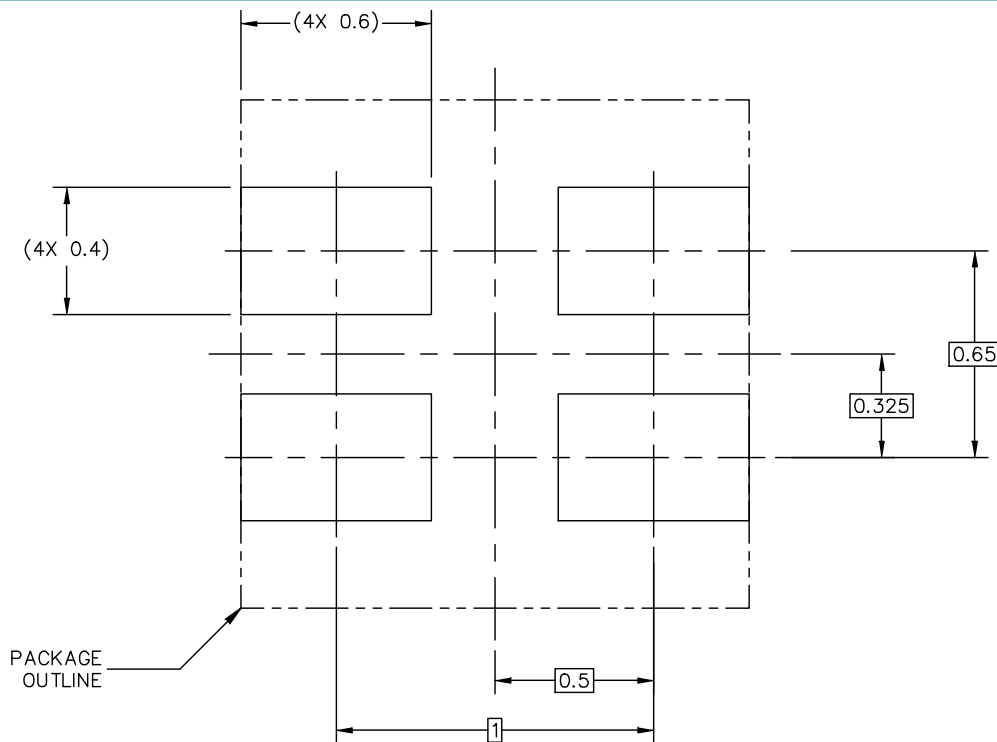
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Figure 3. Reflow soldering footprint part1 for X2SON4 (SOT2017-1)

X2SON4, super thin small outline; no leads, 4 terminals, 0.65 mm pitch, 1.6 mm x 1.6 mm x 0.32 mm body



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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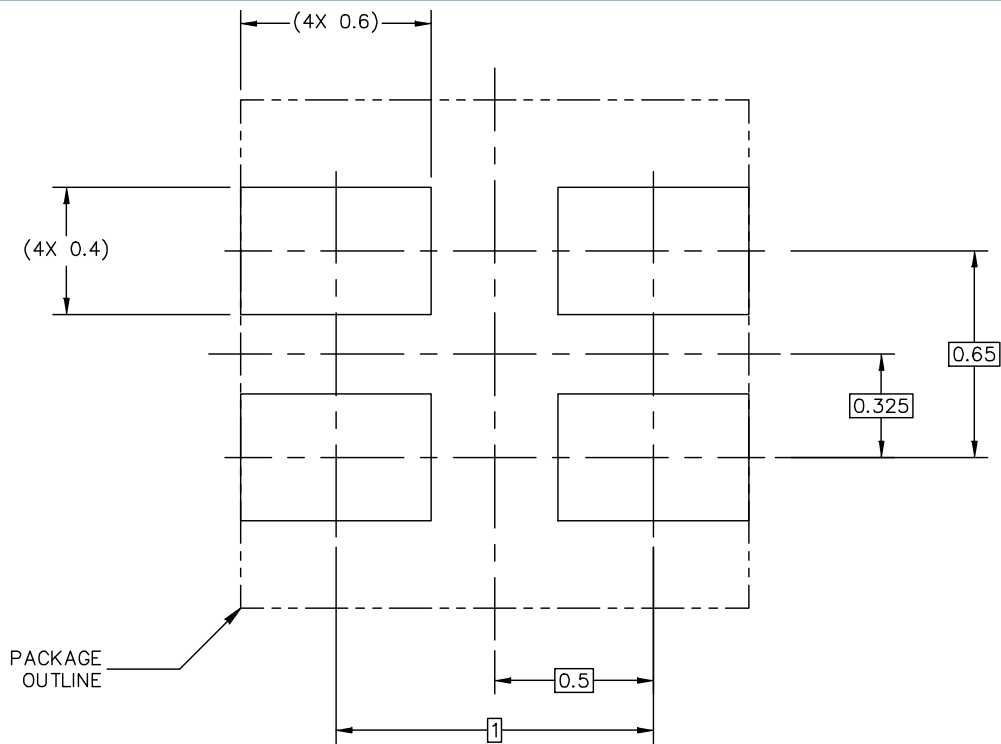
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Figure 4. Reflow soldering footprint part2 for X2SON4 (SOT2017-1)

X2SON4, super thin small outline; no leads, 4 terminals, 0.65 mm pitch, 1.6 mm x 1.6 mm x 0.32 mm body



RECOMMENDED STENCIL THICKNESS 0.125 OR 0.15

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 5. Reflow soldering footprint part3 for X2SON4 (SOT2017-1)

X2SON4, super thin small outline; no leads, 4 terminals, 0.65 mm pitch, 1.6 mm x 1.6 mm x 0.32 mm body

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS.
5. MIN. METAL GAP SHOULD BE 0.2 MM.

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Figure 6. Package outline note X2SON4 (SOT2017-1)

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body

4 Legal information

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